

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
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Name	Execution Date
HUI-CHUN YEH	03/05/2013
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Property Type	Number
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DATE SIGNED:	01/12/2018
Total Attachments: 1	
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**COMBINED DECLARATION and ASSIGNMENT (37 CFR 1.63) FOR UTILITY OR
DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76)**

**Title of
Invention**

LIGHT-EMITTING DIODE DEVICE

As the below named inventor, I hereby declare that:

This declaration ☒ The attached application, or
is directed to:

☐ United States application or PCT international application number _____
filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the application and am aware of the duty to disclose to the US Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR § 1.56.

ASSIGNMENT

For good and valuable consideration, the receipt, sufficiency and adequacy of which are hereby acknowledged, I hereby sell, assign, and transfer to Epistar Corporation, having a principle place of business at Hsinchu city, Taiwan, and its successors, assigns, and legal representatives, my entire right, title and interest in and to the invention listed above, together with the Application, any and all Patents that may issue for the United States and all foreign countries (including the right to claim priority under the terms of the International Convention and any other relevant International Treaties and Arrangements from the aforesaid application), in and to any and all improvements that are disclosed in the above-noted application, and in and to any reissues, renewals, continuations, continuation-in-parts, divisionals or extensions thereof that have been or shall be filed in the United States and all foreign countries on any of said improvements.

I agree that I will communicate to the assignee or its representatives any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, and reissue applications, execute all necessary assignment papers to cause any and all Patents to be issued to the assignee, make all rightful oaths, and, generally do everything possible to aid said assignee, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

LEGAL NAME OF INVENTOR (Given name FAMILY NAME)

Inventor: Hui-chun Yeh

Date: 2013.07.10

Signature: Hui-chun Yeh